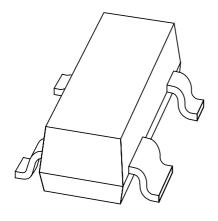
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BAT74**Schottky barrier double diode

Product specification Supersedes data of 1996 Mar 19 2001 Sep 05





## Schottky barrier double diode

**BAT74** 

#### **FEATURES**

- · Low forward voltage
- · Guard ring protected
- Small plastic SMD package.

#### **APPLICATIONS**

- Ultra high-speed switching
- · Voltage clamping
- · Protection circuits
- · Blocking diodes.

#### **DESCRIPTION**

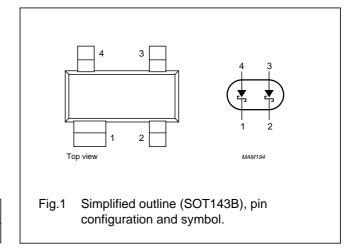
Planar Schottky barrier double diode. Two separate dies encapsulated in a SOT143B small plastic SMD package.

#### **MARKING**

TYPE NUMBER	MARKING CODE		
BAT74	L41		

#### **PINNING**

PIN	DESCRIPTION	
1	cathode (k <sub>1</sub> )	
2	cathode (k <sub>2</sub> )	
3	anode (a <sub>2</sub> )	
4	anode (a <sub>1</sub> )	



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT	
Per diode	Per diode					
$V_R$	continuous reverse voltage		_	30	V	
I <sub>F</sub>	continuous forward current		_	200	mA	
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1 \text{ s}; \ \delta \le 0.5$	_	300	mA	
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> < 10 ms		600	mA	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; see Fig.2	_	230	mW	
T <sub>stg</sub>	storage temperature		-65	+150	°C	
Tj	junction temperature		_	125	O°	
T <sub>amb</sub>	operating ambient temperature		-65	+125	°C	
Double did	Double diode operation					
V <sub>R</sub>	continuous reverse voltage		_	30	٧	
		series connection	_	60	V	
I <sub>F</sub>	continuous forward current		_	110 <sup>(1)</sup>	mA	
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1 \text{ s; } \delta \le 0.5$	_	200	mA	

#### Note

1. If both diodes are in forward operation at the same moment, total device current is max. 110 mA. If one diode is in reverse operation and the other is in forward operation at the same moment, total device current is max. 200 mA.

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# Schottky barrier double diode

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#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Refer to SOT143B standard mounting conditions.

#### **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

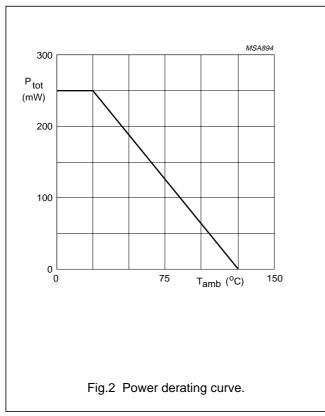
SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
Per diode		·	•	1
V <sub>F</sub>	forward voltage	see Fig.3		
		I <sub>F</sub> = 0.1 mA	240	mV
		I <sub>F</sub> = 1 mA; note 1	320	mV
		I <sub>F</sub> = 10 mA	400	mV
		I <sub>F</sub> = 30 mA	500	mV
		I <sub>F</sub> = 100 mA	800	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 25 V; note 2; see Fig.4	2	μΑ
t <sub>rr</sub>	reverse recovery time	when switched from $I_F$ = 10 mA to $I_R$ = 10 mA; $R_L$ = 100 $\Omega$ ; measured at $I_R$ = 1 mA; see Fig.6	5	ns
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; see Fig.5	10	pF

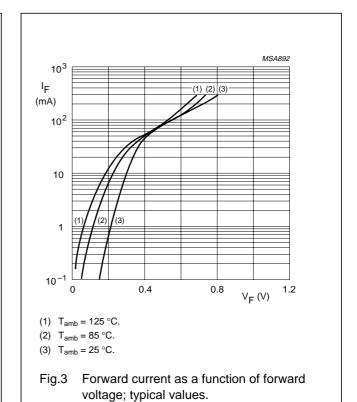
#### **Notes**

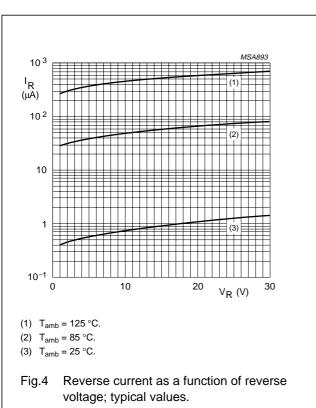
- 1. Temperature coefficient of forward voltage -0.6%/K.
- 2. Pulsed test:  $t_p = 300\mu s$ ;  $\delta = 0.02$ .

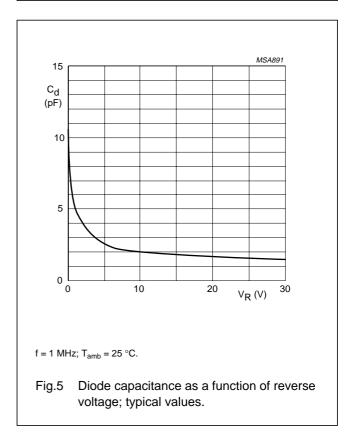
# Schottky barrier double diode

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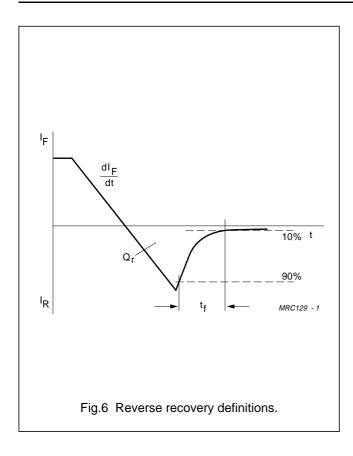






# Schottky barrier double diode

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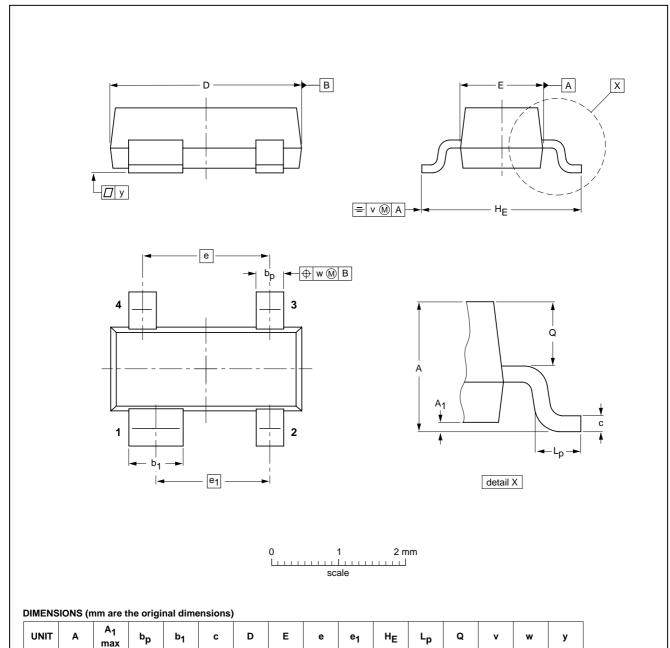
# Schottky barrier double diode

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#### **PACKAGE OUTLINE**

Plastic surface mounted package; 4 leads

SOT143B



OUTLINE	REFERENCES		EUROPEAN	ICCUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT143B						97-02-28

1.9

0.45

0.2

0.1

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0.48

mm

0.88

0.78

0.15

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### Schottky barrier double diode

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#### **DATA SHEET STATUS**

DATA SHEET STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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